TEGO® Twin 4200 –
The new universal wetting and anti-cratering additive

TEGO® Twin 4200 is the new universal substrate wetting additive for waterborne wood coatings, industrial coatings and printing inks, which can also be used in solventborne and even UV cured applications.

In addition to outstanding wetting and anti-cratering properties, TEGO® Twin 4200 does not stabilize foam, providing a robust, more simplified processing during the paint manufacturing.

Enhanced reduction of surface tension and high compatibility lead to a high performance product ideal for various coating systems. Additionally, TEGO® Twin 4200’s 100% active matter content allows for its use in modern zero VOC formulations.

If you have questions regarding this product or any of the others within our expansive portfolio, please visit the Evonik booth (#1707) at the 2014 American Coatings Show, held April 8–10 in Atlanta, Ga.

Company Information
Evonik, the creative industrial group from Germany, is one of the world leaders in specialty chemicals. Profitable growth and a sustained increase in the value of the company form the heart of Evonik’s corporate strategy. Its activities focus on the key megatrends health, nutrition, resource efficiency and globalization. Evonik benefits specifically from its innovative prowess and integrated technology platforms.

Evonik is active in over 100 countries around the world. In fiscal 2012 more than 33,000 employees generated sales of around €13.4 billion and an operating profit (adjusted EBITDA) of about €2.4 billion (excluding Real Estate in both cases).

Disclaimer
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